CLAIMS

1. A sealing composition comprising:

an epoxy resin,

a curing agent,

an inorganic filler, and

an unbaked hydrotalcite compound having a mole ratio of Mg ion to Al ion (Mg/Al) of 2.4 or more,

wherein the inorganic filler comprises magnesium oxide, and a content of the magnesium oxide is from 1 part by mass to 30 parts by mass with respect to 100 parts by mass of the epoxy resin.

2. The sealing composition according to claim 1, wherein a content of the unbaked hydrotalcite compound is from 1 part by mass to 15 parts by mass with respect to 100 parts by mass of the epoxy resin.

3. The sealing composition according to claim 1 or 2, wherein a content of the inorganic filler is from 75% by mass to 97% by mass with respect to the sealing composition.

4. A sealing composition according to any one of claims 1 to 3

wherein the unbaked hydrotalcite compound comprises a compound represented by the following Formula (1),

$$Mg_{1-x}Al_x(OH)_2(CO_3)_{x/2}\bullet mH_2O \qquad \text{Formula (1)}$$

wherein, in Formula (1), each of x and m independently represents a positive number.

5. The sealing composition according to any one of claims 1 to 4, further comprising a curing accelerator.

6. A semiconductor device comprising:

a semiconductor element, and

a cured product of the sealing composition according to any one of claims 1 to 4, which seals the semiconductor element.